temperature to normal temperature. Even if the substrate strips 100 are controlled in the same process and made of the same material, the shrinkage of the substrate strip 100 is still different. Therefore, each substrate strip 100 needs to be measured to define the cutting tracks in the first phase and the second phase. Then the saw machine detects the reference point of the alignment of the substrate areas 110 and moves to the predetermined position to cut the substrate strip 100 along the cutting tracks 101. Because the saw machine cuts the substrate strips 100 (which have different shrinkage) by the predetermined cutting tracks 101, the cutting error A of each substrate area 110 adds to the peripheral substrate areas 110 in all dimensions on the substrate strips 100, even though the cutting tracks are predetermined.

Page 2, between lines 3 and 4, please insert the following title centered in the middle of the page:

--Summary of the Invention--

Page 2, line 12, delete in its entirety, i.e., "Summary of the Invention".

Page 2, lines 13-18, please amend this paragraph as follows:

--The primary objective of this invention is to provide a substrate sawing process for a strip of substrate that includes multi-alignment so a sawing machine can be mechanically moved to the substrate areas and can be positioned by the corresponding alignments of each of the substrate areas to reduce the cutting error. Because the saw machine is positioned on each substrate areas by corresponding alignment, a cutting error in any of the substrate areas will not accumulate to the subsequent substrate areas or substrate strips.--